

METHOD FOR TEMPORARY BONDING WORKPIECE AND ADHESIVE

ABSTRACT

A method for temporary bonding workpiece includes steps as follows. A combining step is performed, wherein an adhesive layer is formed on a surface of at least one substrate and/or at least one workpiece. A bonding step is performed, wherein the substrate and the workpiece are bonded by the adhesive layer. A processing step is performed, wherein the workpiece is processed. A debonding step is performed, wherein the adhesive layer is irradiated with a laser so as to separate the workpiece from the substrate. The adhesive layer is formed by an adhesive, the adhesive includes a polymer and a light absorbing material, a content of the polymer in a solid content of the adhesive is in a range of 50 wt% to 98 wt%, a content of the light absorbing material in the solid content of the adhesive is in a range of 2 wt% to 50 wt%.

FIG. 1